

CPMT Officers

President:	William T. Chen	+1-408-986-6505
VP (Technical):	N.Rao Bonda	+1-480-413-6121
VP (Conferences):	Rolf Aschenbrenner	+49-30-46403-164
VP (Publications):	Paul B. Wesling	+1-408-331-0114
VP (Education):	Albert F. Puttlitz	+1-802-899-4692
VP (Finance):	Thomas G. Reynolds III	+1-850-897-7323
Sr. Past Pres.:	Rao Tummala	+1-404-894-9097
Jr. Past Pres.:	Phil Garrou	+1-919-248-9261
Executive Director:	Marsha Tickman	+1-732-562-5529

Elected Board Members

2009:
Philip C.H. Chan, Paul D. Franzon, R. Wayne Johnson, Kwang-Lung Lin, Petri Savolainen, and Leonard W. Schaper

2008:
Vasudeva P. Atluri, Li Li, Dongkai Shangguan, Patrick Thompson, Klaus-Jürgen Wolter, and Kishio Yokouchi

2007:
Eric O. Beyne, Steve J. Bezuk, Bahgat Sammakia, Rajen Chanchani, Kitty Pearsall, and C.P. Wong

CPMT Society Newsletter

Editor-in-Chief: Vasudeva P. Atluri, email: vpatluri@ieee.org
Tel: +1-480-554-0360, FAX: +1-480-563-0049

Associate Editor: Li Li, li.li@ieee.org, +1-480-413-6653

Associate Editor: Debendra Mallik, dmallik@ieee.org, +1-480-554-5328

CPMT Archival Publications

Publications VP:
Paul Wesling, +1 408 331 0114; p.wesling@ieee.org

Editor-in-Chief, CPMT Transactions:
Avram Bar-Cohen, Univ. of Maryland, +1-301-405-3173, abc@eng.umd.edu

Transactions on Components & Pkg. Technologies, Editors in Chief:
Ricky S.W. Lee, Hong Kong Univ of Science & Technology, +852-2358-7203; rickleey@ust.hk
Koneru Ramakrishna, Freescale, Inc., +1-512-933-2555; rama@ieee.org

Transactions on Advanced Packaging, Editor in Chief:
G. Subbarayan, Purdue University, Mechanical Engineering Dept., +1-765-494-9770; ganeshs@purdue.edu
José E. Schutt-Ainé, University of Illinois at Urbana-Champaign, +1-217-244-7279, jose@emlab.uiuc.edu

Transactions on Electronics Pkg. Manufacturing, Editor in Chief:
R. Wayne Johnson, +1-334-844-1880, johnson@eng.auburn.edu

Technical Committee Chairs

TC-Assy - IC and Package Assembly:
Martin Goetz, IBM, +1-919-486-2409, mgoetz@us.ibm.com

TC-ASTR - Environmental Stress & Reliability Test:
John E. Proulx, GM ATC, +1-310-257-3714, john.proulx@gm.com

TC-ECCC - Electrical Contacts, Connectors and Cables:
Jerry Witter, Chugai USA Inc., +1-847-244-6025, g.witter@ieee.org

TC-Ed - Education:
Rao R. Tummala, Georgia Tech., +1-404-894-9097, rao.tummala@ee.gatech.edu

TC-EDMS - Electrical Design, Modeling and Simulation:
Madhavan Swaminathan, Georgia Tech, +1-404-894-3340, madhavan.swaminathan@ee.gatech.edu

TC-EM - Manufacturing - Design & Process:
Walter J. Trybula, +1-512-356-3306, w.trybula@ieee.org

TC-GEMP - Green Electronics Manufacturing and Packaging:
Nils F. Nissen, IZM, Berlin, +49-30-46403-139, nils.nissen@izm.fraunhofer.de

TC-HDSB - High Density PWB Packaging:
Yoshitaka Fukuoka, Weisti, +81-3-3475-0755, weisti.fukuoka@rose.zero.ad.jp

TC-M - Materials:
Rajen Chanchani, Sandia Labs, +1-505-844-3482, r.chanchani@ieee.org

TC-MEMS - MEMS and Sensor Packaging:
Eric Jung, IZM, Berlin, +49-30-46403-161, email: erju@izm.fhg.de

TC-NANO - Nano Packaging:
Rao Tummala, Georgia Tech., +1-404-894-9097, rao.tummala@ee.gatech.edu

TC-OPTO - Fiber Optics & Photonics:
Susan Law, Australian Photonics/OFTC, +612-9351-1960, Email: s.law@oftc.usyd.edu.au

TC-PEP - Power Electronics Packaging:
Douglas Hopkins, SUNY Buffalo, +1-607-729-9949, d.hopkins@ieee.org

TC-RF+W - RF and Wireless:
Craig A. Gaw, Freescale, +1-480-413-5920, c.a.gaw@ieee.org

TC-SP - Systems Packaging:
Cian O Mathuna, +353-21-4904350, cian.omathuna@tyndall.ie

TC-Test - Electrical Test:
Bruce Kim, Univ of Alabama, +1-205-348-4972, bruce.kim@ieee.org

TC-Therm - Thermal Management & Thermomech. Design:
Tony Mak, Dallas Semiconductor, +1-972-371-4364, t.mak@ieee.org

TC-WLP - Wafer Level Packaging:
Michael Toepper, IZM, Berlin, +49-30-46403-603, toepper@izm.fhg.de

Strategic Program Directors

Awards and Recognition: Kitty Pearsall, kittyp@us.ibm.com

Conferences: Rolf Aschenbrenner, wdb@engr.uark.edu

ECTC Integration: C.P. Wong, cp.wong@ieee.org

Educational Programs: Albert F. Puttlitz, a.f.puttlitz@ieee.org

Global Chapters and Membership: Ralph W. Russell, II, r.w.russell@ieee.org

Publications: Paul B. Wesling, p.wesling@ieee.org

Student Programs: William D. Brown, wdb@engr.uark.edu

Technical Programs: N.Rao Bonda, r.bonda@ieee.org

Region 8 Programs: Johan Liu, johan.liu@me.chalmers.se

Region 10 Programs: Charles Lee, charles.lee@ieee.org

Standing Committee Chairs

Awards: Kitty Pearsall, kittyp@us.ibm.com

Chapter Development: Ralph W. Russell, II, r.w.russell@ieee.org

Constitution and Bylaws: Tony Mak, t.mak@ieee.org

Distinguished Lecturers: Albert F. Puttlitz, a.f.puttlitz@ieee.org

Educational Activities: Vacant

Fellows Evaluation: Ching-Ping (C.P.) Wong, cp.wong@ieee.org

Fellows Search: David W. Palmer, d.palmer@ieee.org
Rao Tummala, rao.tummala@ee.gatech.edu

Finance: Philip E. Garrou, pgarrou@rti.com

Long Range / Strategic Planning: Rao Tummala, rao.tummala@ee.gatech.edu

Membership: Ralph W. Russell, II, r.w.russell@ieee.org

Nominations: Philip E. Garrou, pgarrou@rti.com

Distinguished Lecturers

Program Director: Albert F. Puttlitz

Lecturers: Avram Bar-Chen, H. Anthony Chan, Paul Franzon, George Harman, Badih El-Kareh, George Katopis, John H. Lau, Michael Leppy, Michael Pecht, Lue Martens, James E. Morris, T. Paul Parker, Karl Puttlitz, John M. Segelken, Ephraim Suhir, Paul Totta, Walter Trybula, Rao Tummala, Paul Wesling, C.P. Wong, and Ralph W. Wyndrum, Jr.

Chapters and Student Branches

Refer to www.cpmt.org for CPMT Society Chapters and Student Branches list

IEEE Components, Packaging, and Manufacturing Technology Society Newsletter is published quarterly by the Components, Packaging, and Manufacturing Technology Society of the Institute of Electrical and Electronics Engineers, Inc. Headquarters: 3 Park Avenue, 17th Floor, New York, NY 10016-5997. US \$1.00 per member per year is included in Society fee for each member of the Components, Packaging, and Manufacturing Technology Society. Printed in U.S.A. Periodicals postage paid at New York, NY, and at additional mailing offices. Postmaster: Send address changes to IEEE CPMT Newsletter, IEEE 445 Hoes Lane, Piscataway, NJ 08854. All rights reserved, copyright (c) 2005 by the CPMT Society of IEEE. Authors and Artists given full permission for further use of their contributions. For circulation information call IEEE Customer Service 800-701-4333, or FAX 908-981-9667.



**2007 Deadlines for Submitting Articles:
November 25th, 2007**

**Only Articles Sent to nsltr-input@cpmt.org
will be included in the newsletter**

Members-only Web (www.cpmt.org/mem/)

**UserName: [available to Members --
Password: join CPMT!]**